SOT2048-1

FCD34, flip chip die, 34 terminals, 0.4 mm pitch, 2.45 mm x 2.87 mm x 0.091 mm body

31 August 2020

1   Package summary

Terminal position code	B (bottom)
Package type descriptive code	FCD34
Package style descriptive code	FCD (flip chip die)
Mounting method type	S (surface mount)
Issue date	21-05-2020
Manufacturer package code	98ASA01527D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.42	2.45	2.48	mm
package width	2.84	2.87	2.9	mm
package height	-	0.091	0.118	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	34	-	

2 Package outline

FLIP CHIP DIE-34 I/O
2.45 X 2.87 X 0.091 PKG, 0.4 PITCH

SOT2048-1

DETAIL F

TOP VIEW

BOTTOM VIEW

VIEW D-D

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DATE: 21 MAY 2020

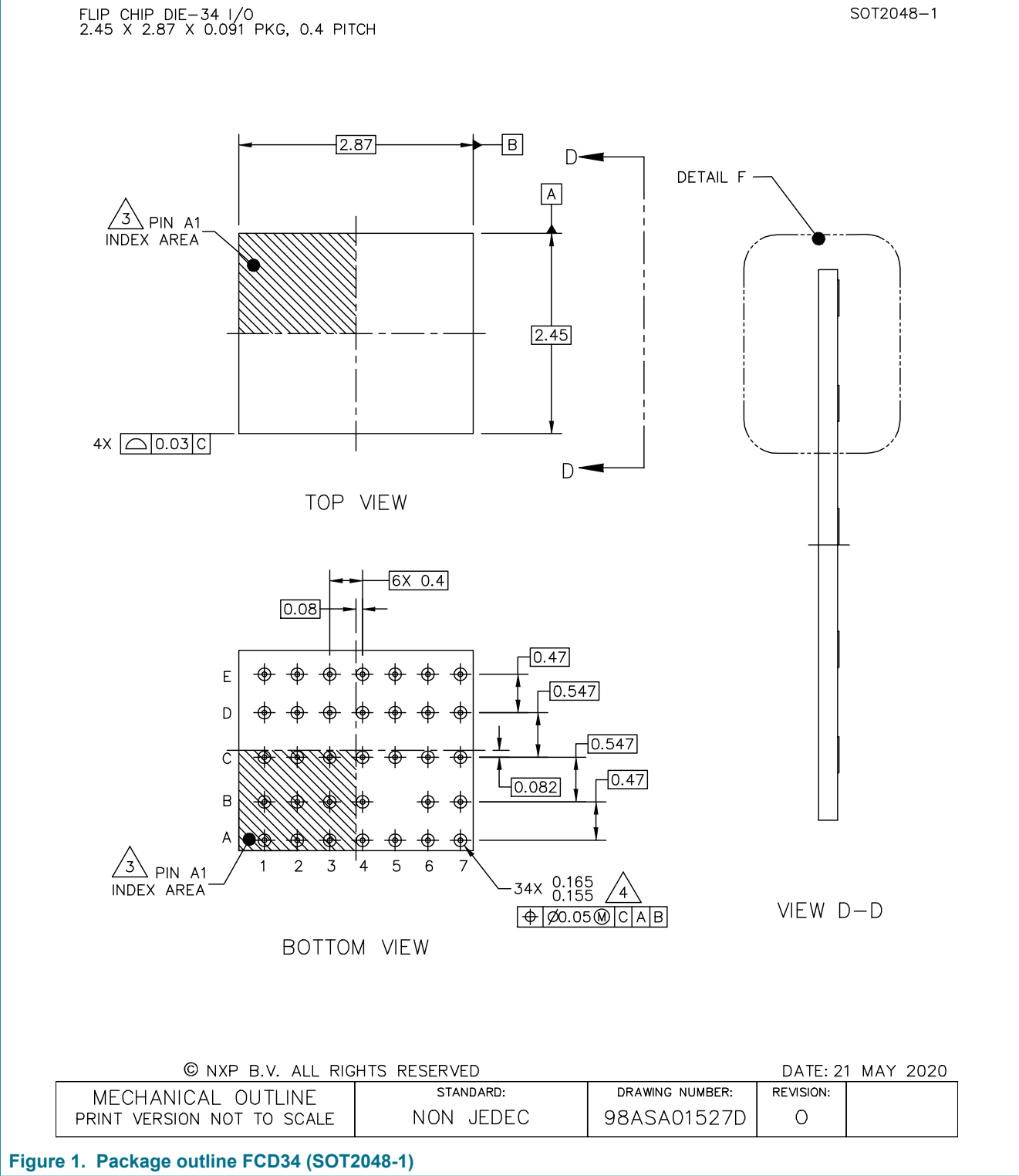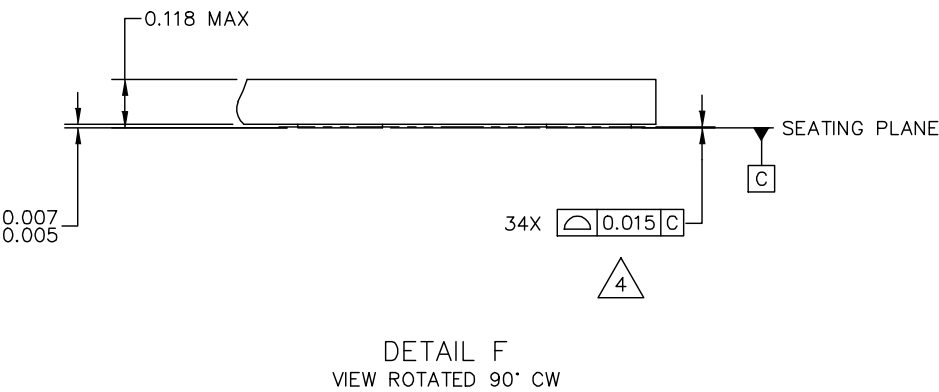| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01527D	REVISION: O

Figure 1. Package outline FCD34 (SOT2048-1)

FLIP CHIP DIE-34 I/O
2.45 X 2.87 X 0.091 PKG, 0.4 PITCH

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0.118 MAX

SEATING PLANE

C

0.007
0.005

34X   △ 0.015 C

△4

DETAIL F
VIEW ROTATED 90° CW

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Figure 2. Package outline detail of FCD34 (SOT2048-1)

FLIP CHIP DIE—34 I/O
2.45 X 2.87 X 0.091 PKG, 0.4 PITCH

SOT2048−1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. DIMENSIONS APPLY TO ALL PINS.

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Figure 3. Package outline note FCD34 (SOT2048-1)

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Package information

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3 Legal information

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